



BSI Standards Publication

Test methods for electrical materials, printed boards and other interconnection structures and assemblies

Part 2-807: Test methods for materials for interconnection structures — Decomposition temperature (T_d) using TGA

National foreword

This British Standard is the UK implementation of EN IEC 61189-2-807:2021. It is identical to IEC 61189-2-807:2021.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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